

**TM15N06SI**
**N-Channel Enhancement Mosfet**
**General Description**

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

**Applications**

- Load switch
- PWM

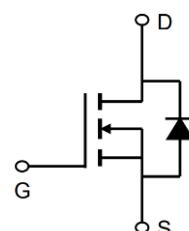
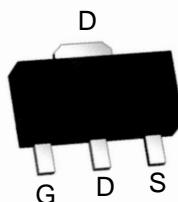
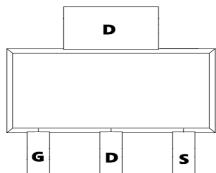
**General Features**

$V_{DS}=60V$   $I_D=15A$   
 $R_{DS(ON)} = 30m\Omega$  (Typ.) @  $V_{GS}=10V$

100% UIS Tested  
100%  $R_g$  Tested



SI:SOT-89-3L



Marking: 15N06

**Absolute Maximum Ratings ( $T_c=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	15	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	10.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	55.5	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	22	mJ
$I_{AS}$	Avalanche Current	23	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	25	°C/W

**TM15N06SI**
**N-Channel Enhancement Mosfet**
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	60	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V},$	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.0	1.6	2.5	V
$R_{\text{DS}(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{\text{GS}}=10\text{V}, I_D=5\text{A}$	-	30	40	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=3\text{A}$	-	39	50	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	948	-	pF
$C_{\text{oss}}$	Output Capacitance		-	58.5	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	49.4	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=30\text{V}, I_D=2.5\text{A}, V_{\text{GS}}=10\text{V}$	-	20.3	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	3.7	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	5.3	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=30\text{V}, I_D=5\text{A}, R_G=1.8\Omega, V_{\text{GS}}=10\text{V}$	-	7.6	-	ns
$t_r$	Turn-on Rise Time		-	20	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	15	-	ns
$t_f$	Turn-off Fall Time		-	24	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	15	A	
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	55.5	A	
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_s=5\text{A}$	-	-	1.2	V
$\text{trr}$	Body Diode Reverse Recovery Time	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	29	-	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge		-	43	-	nC

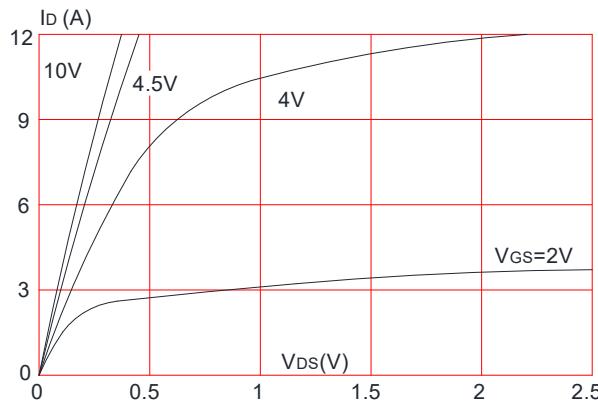
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}, V_{\text{DD}}=30\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega, I_{\text{AS}}=8.7\text{A}$

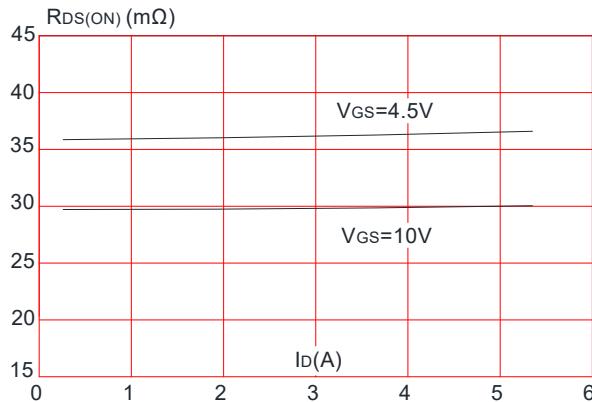
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

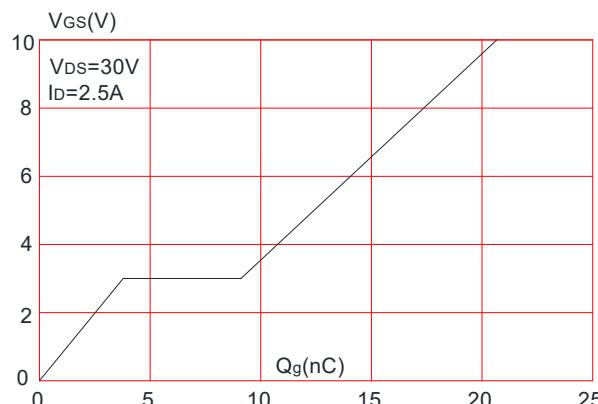
**Figure 1:** Output Characteristics



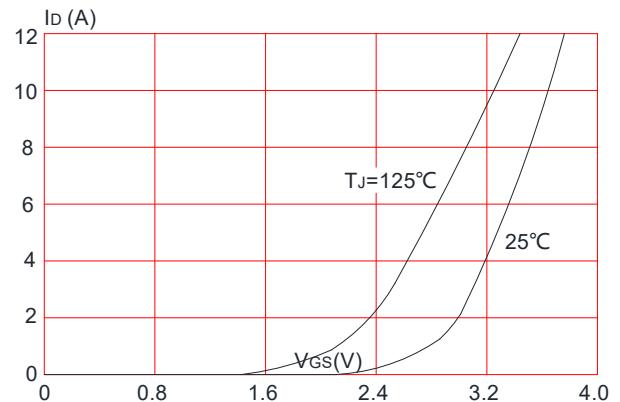
**Figure 3:** On-resistance vs. Drain Current



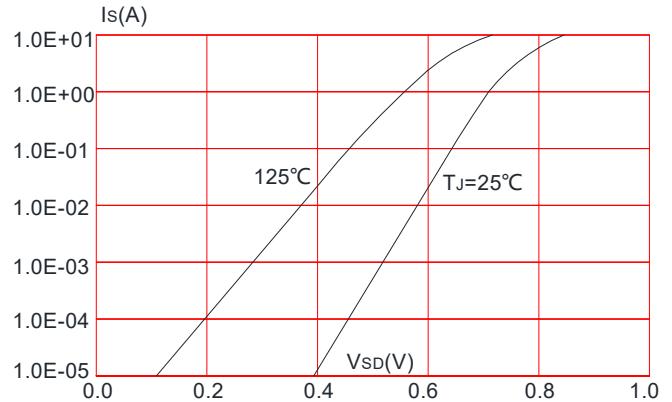
**Figure 5:** Gate Charge Characteristics



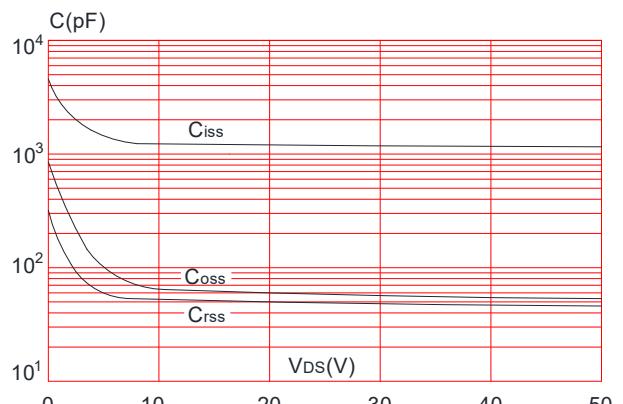
**Figure 2:** Typical Transfer Characteristics



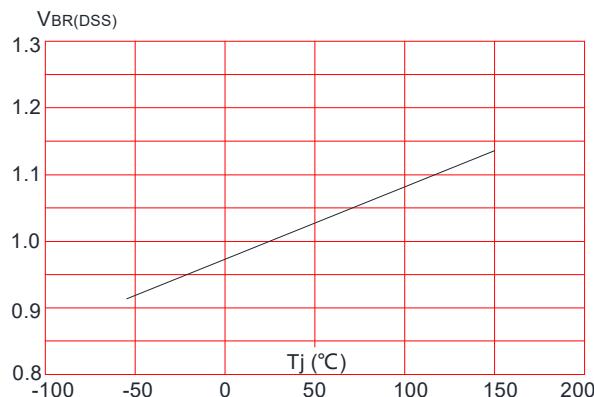
**Figure 4:** Body Diode Characteristics



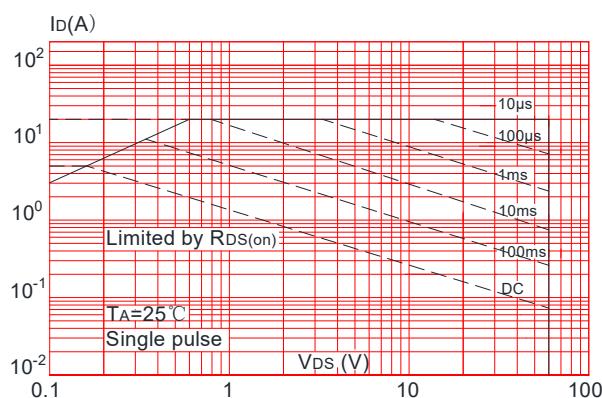
**Figure 6:** Capacitance Characteristics



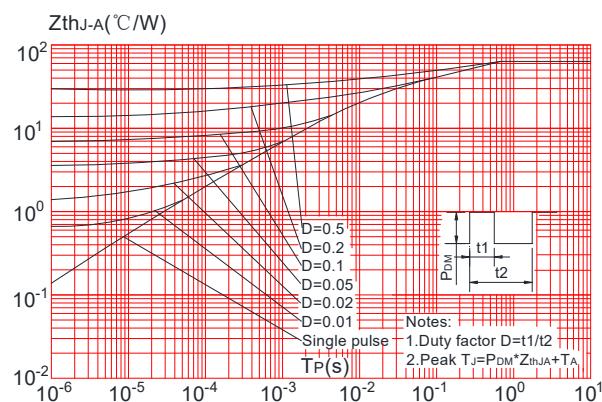
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



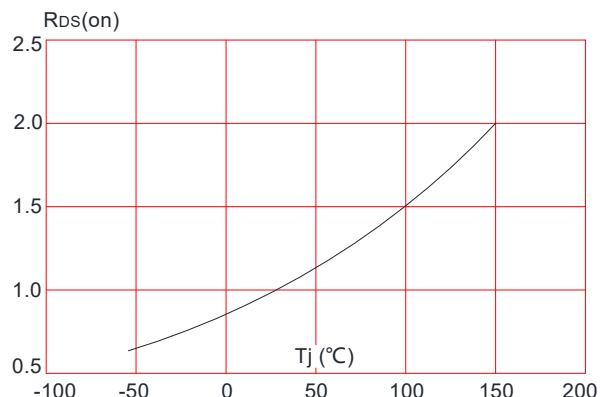
**Figure 9:** Maximum Safe Operating Area



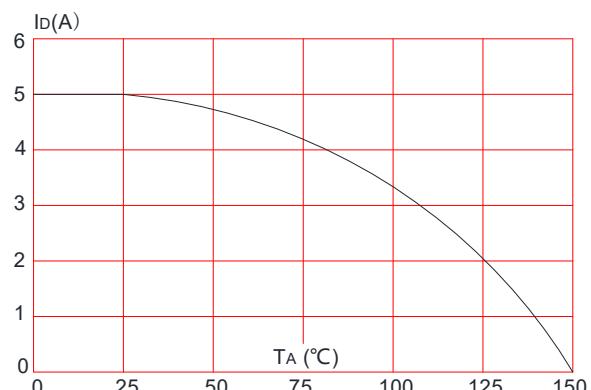
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



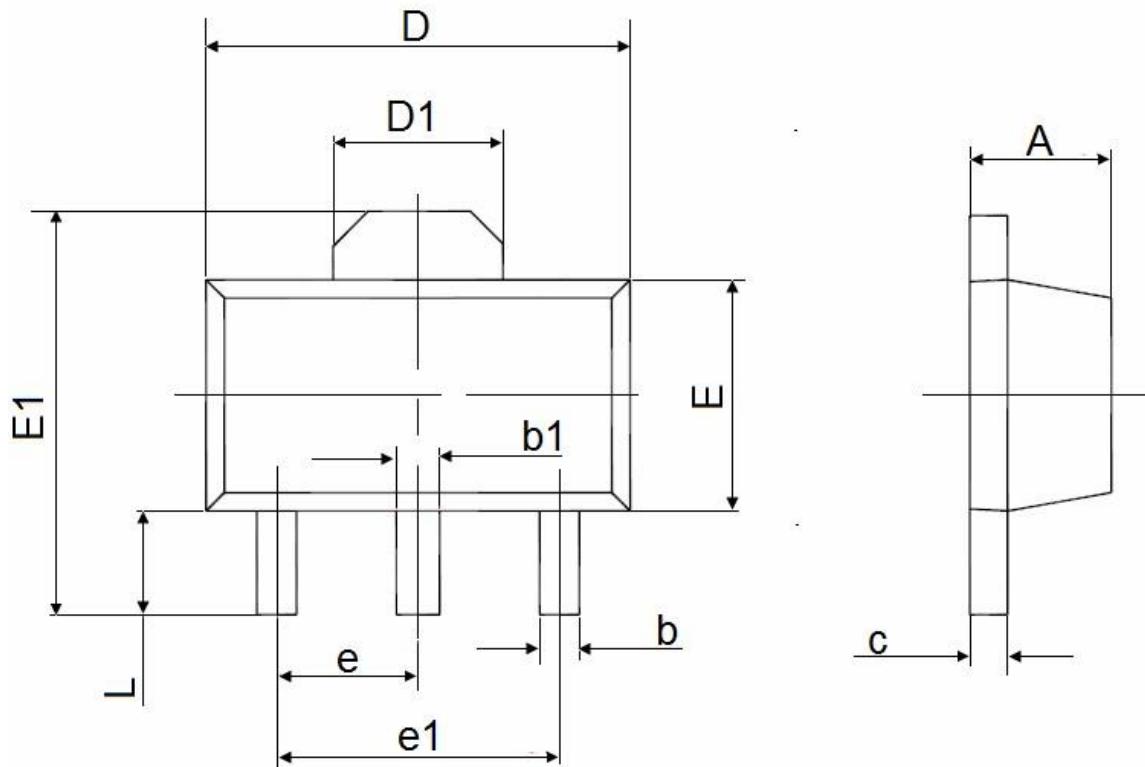
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



## Package Mechanical Data:SOT-89-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047